

Product Summary

$V_{(BR)DSS}$	$R_{DS(on)TYP}$	$I_D@25^{\circ}C$
1200V	165m Ω @18V	21A

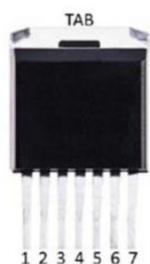
Feature

- Wide bandgap SiC MOSFET technology
- Low On-Resistance with High Blocking Voltage
- Low Capacitances with High-Speed switching
- Low reverse recovery (Qrr)

Application

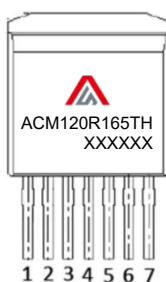
- Switch Mode Power Supplies
- Renewable Energy
- On Board Charger
- High Voltage DC/DC Converters

Package

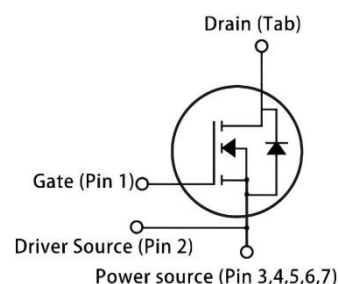


TO-263-7L

Marking



Circuit diagram



Absolute maximum ratings ($T_C=25^{\circ}C$ unless otherwise noted)

Parameter	Symbol	Test Condition	Value	Unit
Drain-Source Voltage	V_{DSmax}	$V_{GS}=0V, I_D=100\mu A$	1200	V
Gate-Source Voltage	V_{GSmax}	AC ($f > 1\text{ Hz}$)	-10/+25	V
Gate-Source Voltage	V_{GSOP}	Static	-4/+18	V
Continuous Drain Current	I_D	$V_{GS}=18V$	21	A
		$V_{GS}=18V, T_C=100^{\circ}C$	15	A
Pulsed Drain Current	$I_{D,pulse}$	Pulse with t_p limited by T_{Jmax}	30	A
Power Dissipation	P_D	$T_J=175^{\circ}C$	112	W
Thermal Resistance (Typ)	$R_{\theta JC}$	Junction to Case	1.34	$^{\circ}C/W$
Junction Temperature	T_J		-55 ~ +175	$^{\circ}C$
Storage Temperature	T_{STG}		-55 ~ +175	$^{\circ}C$

Electrical characteristics (T_J=25°C unless otherwise noted)

Parameter	Symbol	Test Condition	Min.	Typ.	Max.	Unit
Static Characteristics						
Drain-source breakdown voltage	V _{(BR)DSS}	V _{GS} =0V, I _D =100μA	1200			V
Zero gate voltage drain current	I _{DSS}	V _{DS} =1200V, V _{GS} =0V			50	μA
Gate-Source leakage current	I _{GSS}	V _{DS} =0V, V _{GS} =18V			250	nA
Gate threshold voltage	V _{GS(th)}	V _{DS} =V _{GS} , I _D =2.5mA		3		V
		V _{DS} =V _{GS} , I _D =2.5mA, T _J =175°C		2		
Drain-source on-resistance	R _{DS(on)}	V _{GS} =18V, I _D =10A		165	240	mΩ
		V _{GS} =20V, I _D =10A		160		
		V _{GS} =18V, I _D =10A, T _J =175°C		330		
		V _{GS} =20V, I _D =10A, T _J =175°C		320		
Transconductance	g _{fs}	V _{GS} =18V, I _D =10A		9.7		S
		V _{GS} =18V, I _D =10A, T _J =175°C		6		
Dynamic characteristics						
Input Capacitance	C _{iss}	V _{DS} =1000V, V _{GS} =0V V _{AC} =25mV, f =1MHz		730		pF
Output Capacitance	C _{oss}			24		
Reverse Transfer Capacitance	C _{rss}			1		
Total Gate Charge	Q _g	V _{DS} =800V, V _{GS} =-4V/+18V I _D =10A		41		nC
Gate-Source Charge	Q _{gs}			8.4		
Gate-Drain Charge	Q _{gd}			15		
Internal Gate Resistance	R _{G(int)}	f =1MHz, V _{AC} =25mV		3		Ω
Turn-on delay time	t _{d(on)}	V _{DS} =800V, V _{GS} =-4/+18V I _D =10A, R _{G(ext)} =5Ω, L =620μH		2		nS
Turn-on rise time	t _r			8		
Turn-off delay time	t _{d(off)}			11		
Turn-off fall time	t _f			9		
Turn-On Energy	E _{on}			47		μJ
Turn-Off Energy	E _{off}			37		
Total switching energy	E _{tot}			84		
Source-Drain Diode characteristics						
Diode Forward Current	I _S	V _{GS} =-4V, T _C =25°C		24		A
Diode Forward voltage	V _{SD}	V _{GS} =-4V, I _{SD} =3A		3.6		V
		V _{GS} =-4V, I _{SD} =3A, T _J =175°C		3.1		
Reverse Recovery Time	T _{rr}	V _{GS} =-4V, V _R =800V, I _{SD} =10A dif/dt =1000 A/μs		61		nS
Reverse Recovery Charge	Q _{rr}			112		nC
Peak Reverse Recovery Current	I _{rrm}			5		A

Typical Characteristics

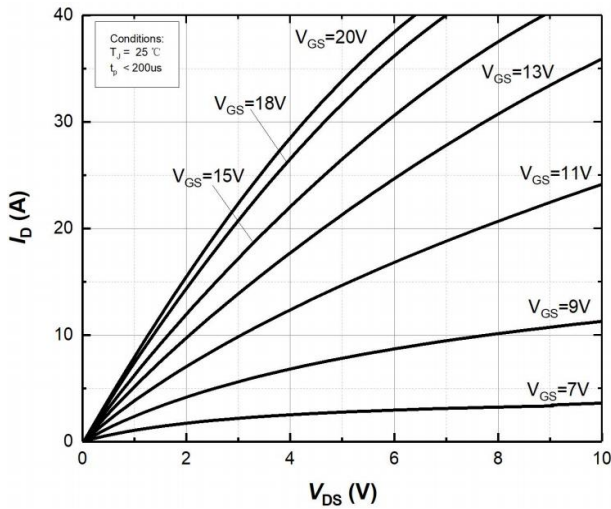


Figure 1. Output characteristics at $T_j=25^\circ\text{C}$

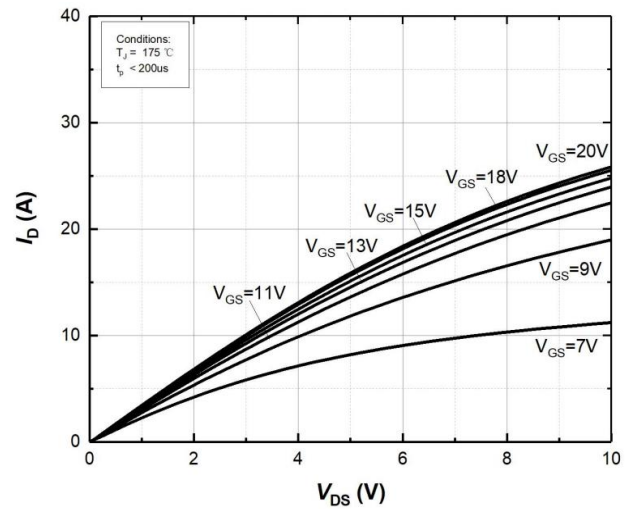


Figure 2. Output characteristics at $T_j=175^\circ\text{C}$

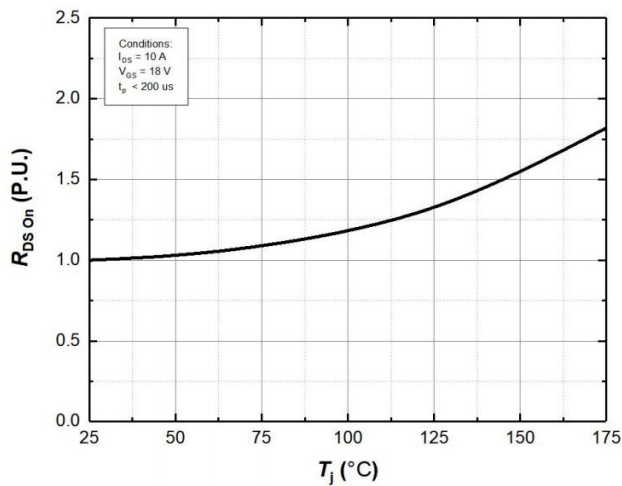


Figure 3. Normalized On-Resistance vs. Temperature

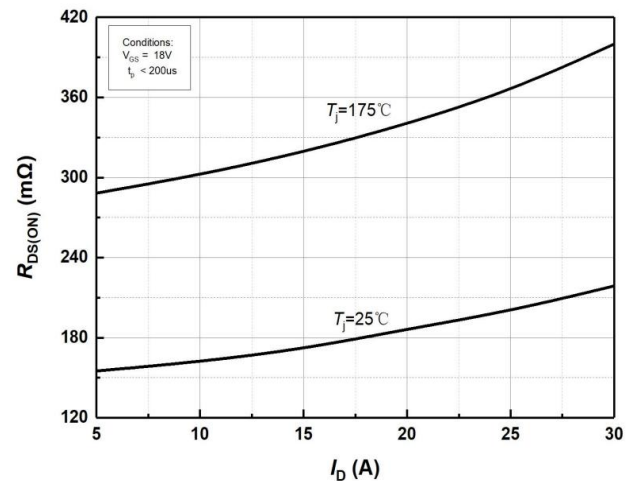


Figure 4. On-Resistance vs. Drain current for Various Temperature

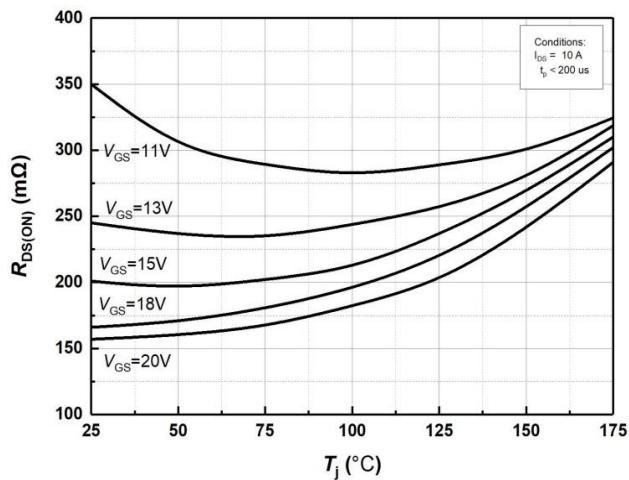


Figure 5. On-Resistance vs. Temperature for Various Gate Voltage

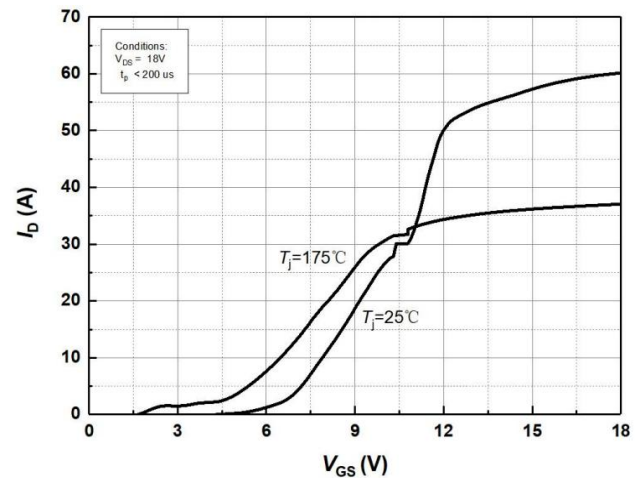


Figure 6. Transfer Characteristics for Various Junction Temperatures

Typical Characteristics

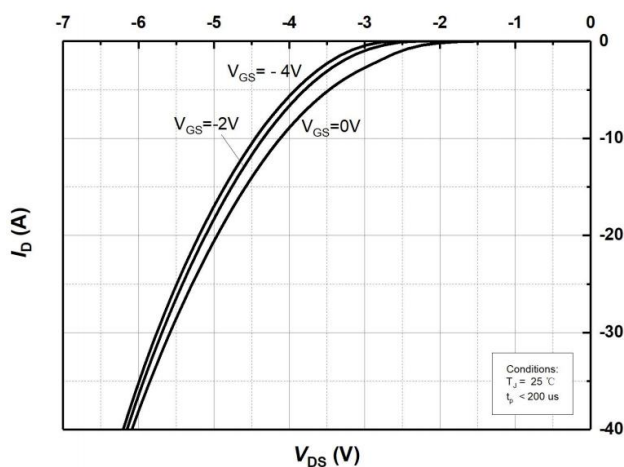


Figure 7. Body Diode Characteristics at Tj=25°C

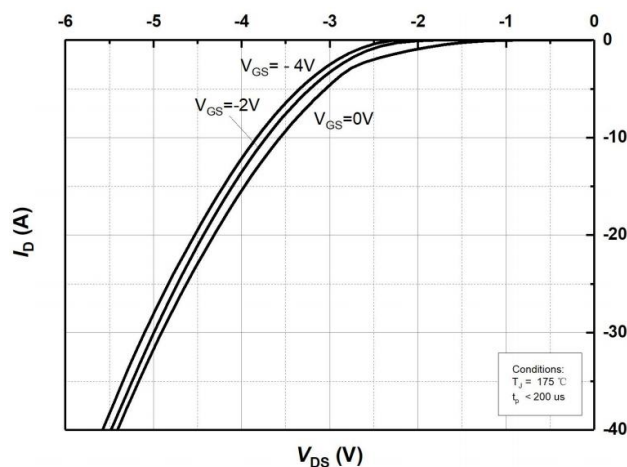


Figure 8. Body Diode Characteristics at Tj=175°C

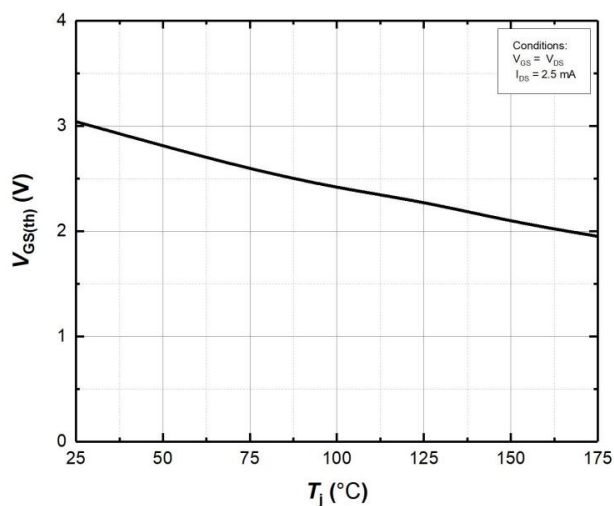


Figure 9. Threshold Voltage vs. Temperature

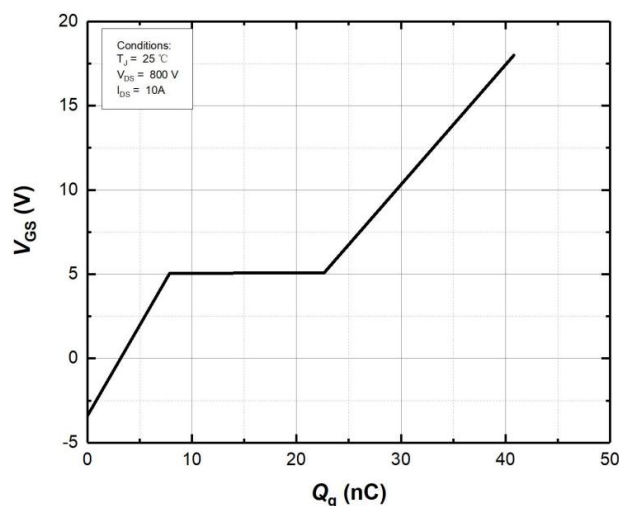


Figure 10 Gate Charge Characteristics

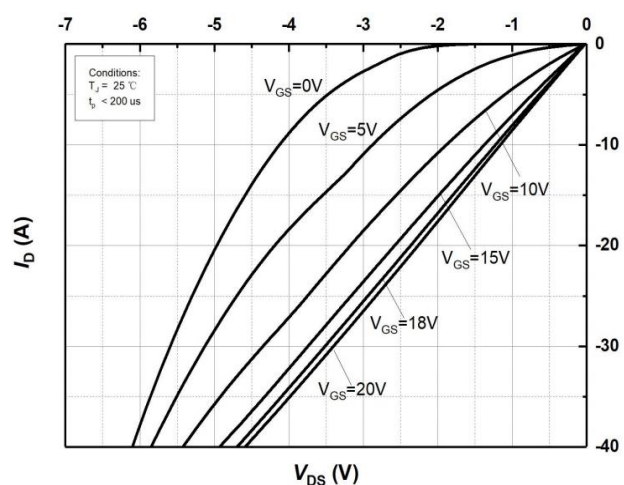


Figure 11. 3rd Quadrant Characteristic at Tj=25°C

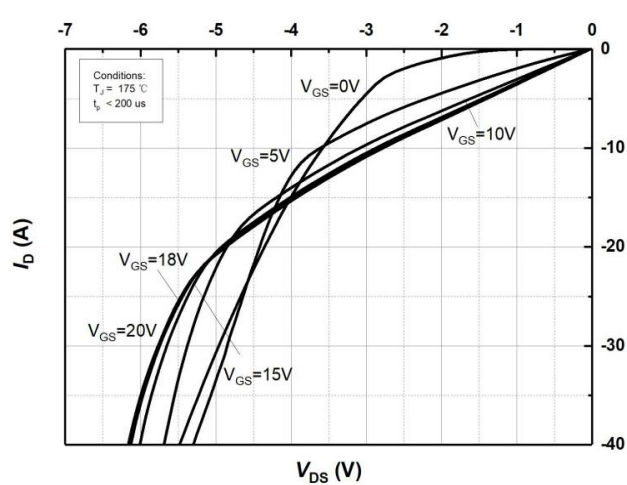


Figure 12. 3rd Quadrant Characteristic at Tj=175°C

Typical Characteristics

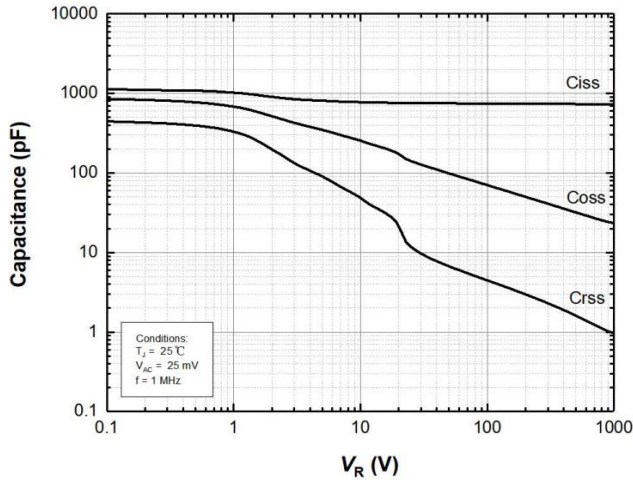


Figure 13. Capacitances vs. Drain-Source Voltage (0 – 1000V)

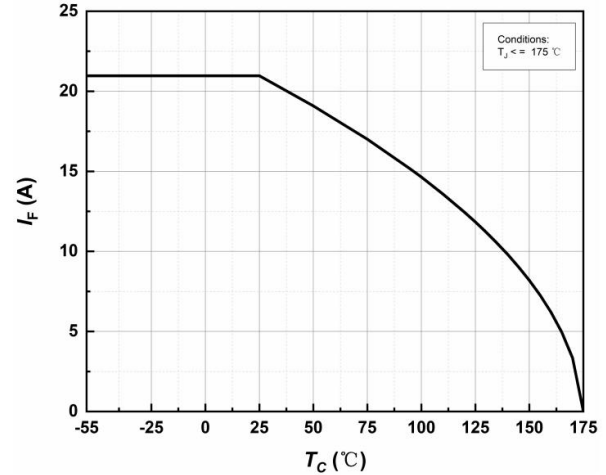


Figure 14. Continuous Drain Current Derating vs Case Temperature

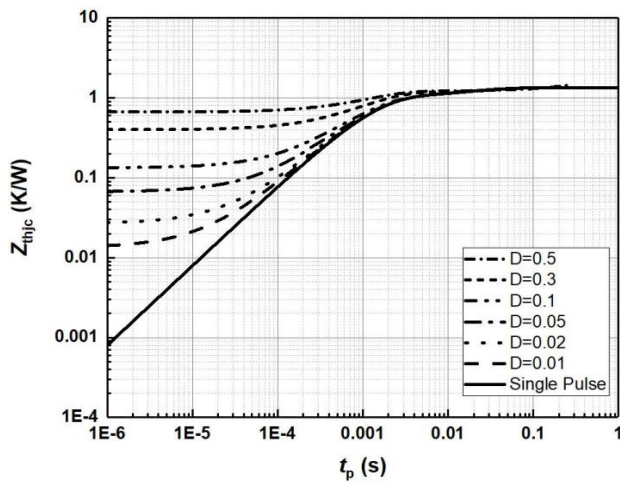


Figure 15. Transient Thermal Impedance (Junction – Case)

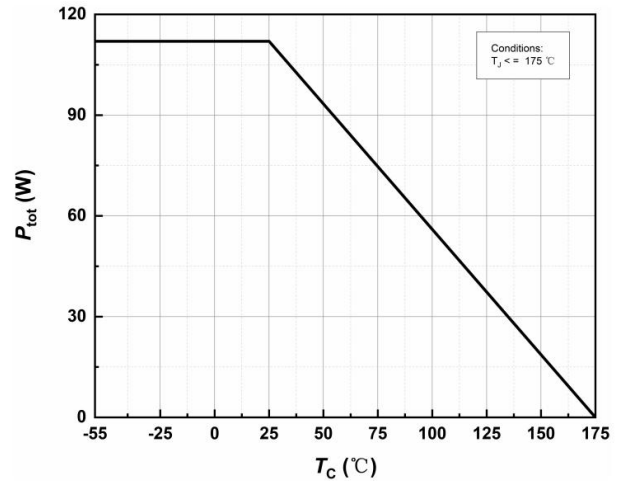


Figure 16. Maximum Power Dissipation Derating vs. Case Temperature

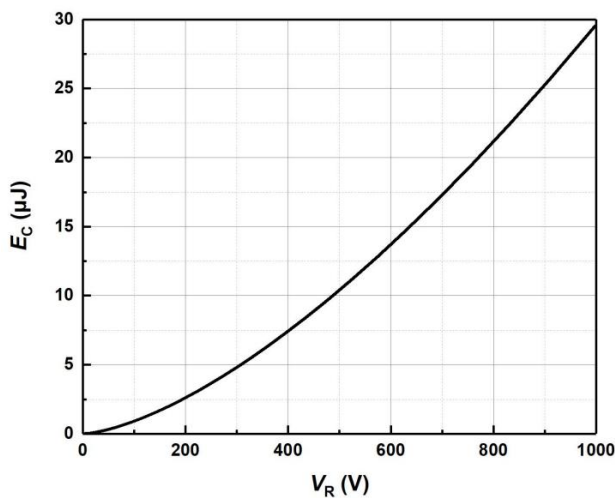


Figure 17. Output Capacitor Stored Energy

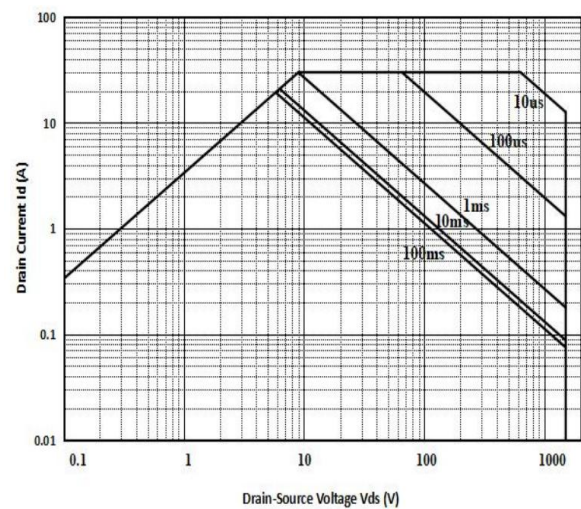


Figure 18. Safe Operating Area

Typical Characteristics

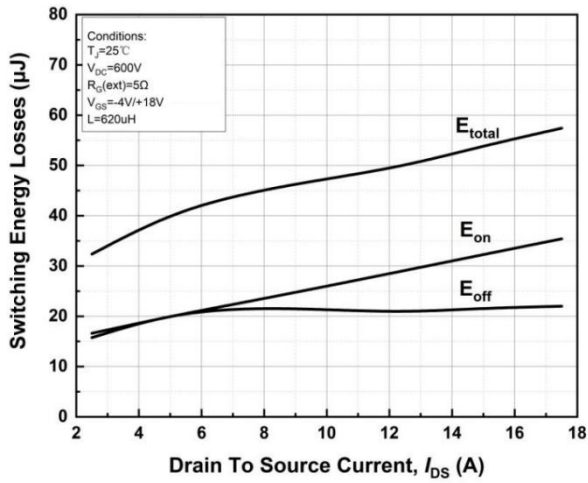


Figure 19. Clamped Inductive Switching Energy vs. Drain Current ($V_{DD} = 600V$)

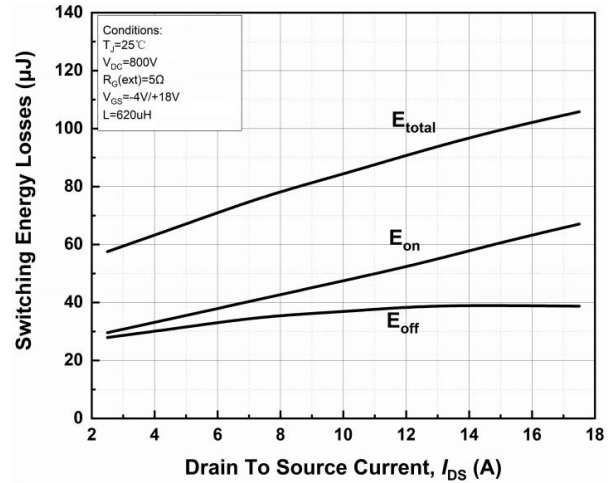


Figure 20. Clamped Inductive Switching Energy vs. Drain Current ($V_{DD} = 800V$)

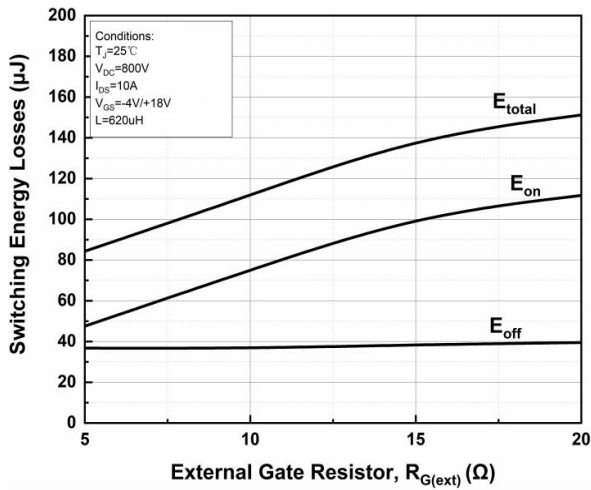


Figure 21. Clamped Inductive Switching Energy vs. $R_{G(ext)}$

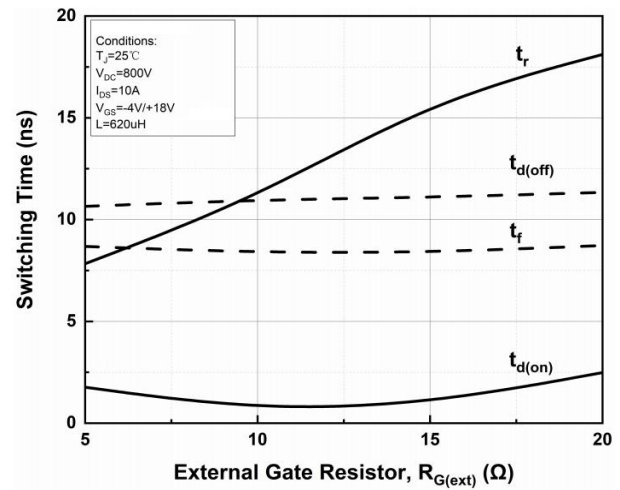
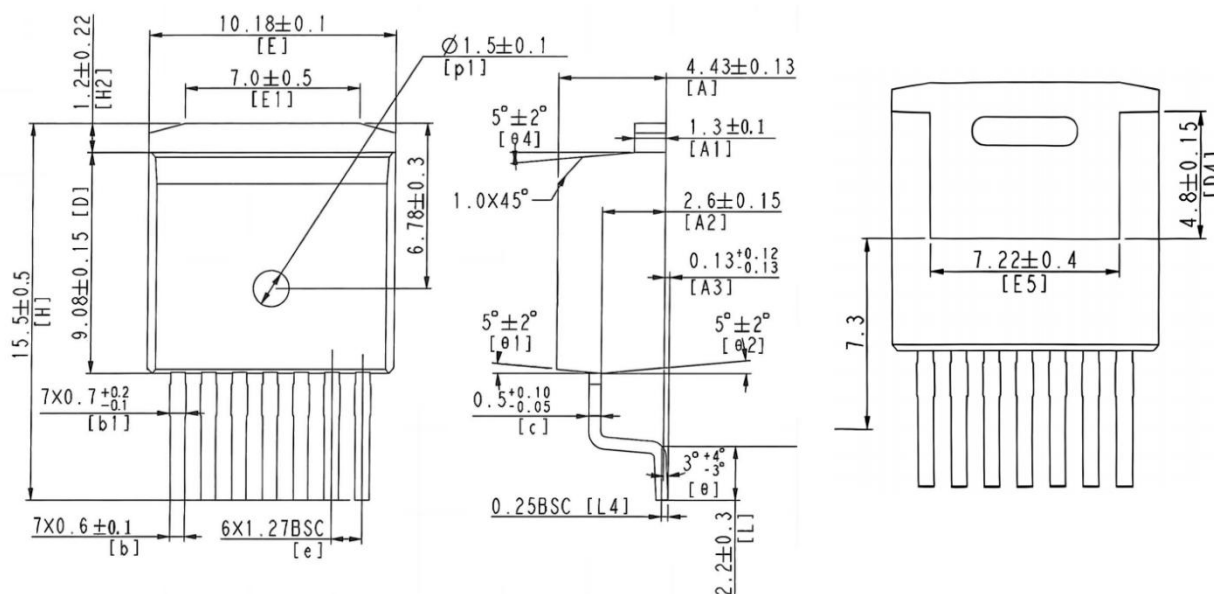


Figure 22. Switching Times vs. $R_{G(ext)}$

TO-263-7L Package Information



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
D	8.930	9.230	0.352	0.363
E	10.080	10.280	0.397	0.405
A	4.300	4.560	0.169	0.180
H	15.000	16.000	0.591	0.630
E1	6.500	7.500	0.256	0.295
E2	6.820	7.620	0.269	0.300
D4	4.650	4.950	0.183	0.195
A1	1.200	1.400	0.047	0.055
A2	2.450	2.750	0.096	0.108
A3	0.000	0.250	0.000	0.010
c	0.450	0.600	0.018	0.024
L	2.000	2.500	0.079	0.098
b	0.500	0.700	0.020	0.028
b1	0.600	0.900	0.024	0.035
e	1.270 BSC.		0.050 BSC	
E5	6.820	7.620	0.269	0.300
L4	0.258 BSC.		0.010 BSC.	
ΦP1	1.400	1.600	0.055	0.063
θ	0°	7°	0°	7°
θ1-4	3°	7°	3°	7°
H2	0.980	1.420	0.039	0.056